Laird
Smart Technology. Delivered.™

86749 Nickel/Copper
Fabric Tape

NI/CU POLYESTER CONDUCTIVE FABRIC TAPE

Laird Technologies' Conductive Fabric Tape 86749 offers exceptional conformability and conductivity for dynamic flex applications. It is constructed of nickel/copper metallized fabric with a conductive pressure sensitive adhesive (PSA). This reliable tape design provides outstanding shielding performance while offering superior abrasion and corrosion resistance under high dynamic flex conditions. The 86749 is a halogen free product and can be supplied in tape or further customized to application by die-cutting or hole punching.

FEATURES RoHS

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity of < 0.06 Ω/□ provides excellent conductivity
- Shielding effectiveness of >62 dB across a wide spectrum of frequencies

MARKETS

ecoGREEN™

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers

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www.lairdtech.com

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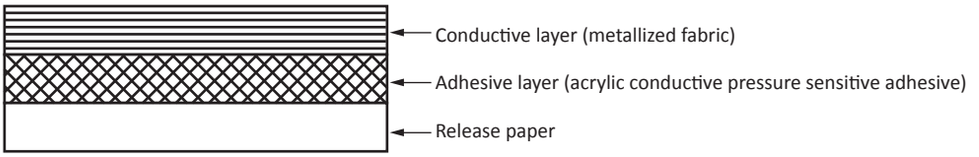
Item	Unit	Value	Test Method
Thickness	mm	0.060 mm ± 0.01	-
Peel Adhesion	Kgf / 25 mm	>0.8	PSTC 101*
Shear Adhesion			
at R.T.	Hrs	>72	PSTC 107#
at 80°C	Hrs	>5	PSTC 107#
Tensile Strength	Kgf / 25 mm	>7	
Operation Temperature	°C	0-80	
Surface Resistivity (Fabric Side)	Ω/□	<0.06	ASTM F390
Z-axial Resistance	Ω	<0.04	
Shielding Effectiveness+			ASTM D4935
at 100 MHz	dB	62	
at 1GHz	dB	68	
Package Dimensions (Max. Width: 1000 mm)	M	W: Dimension by Customer Spec L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		Six Months	

*:Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm +:Typical value

Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

COMPOSITION OF PRODUCT



APPLICATION TECHNIQUES

1. Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
2. To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
3. Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.

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